



20V P-Channel MOSFETs

General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

| BV_{DSS} | $R_{DS(ON)}$ | I_D |
|------------|---------------|--------|
| -20 V | 28 m Ω | -8.5 A |

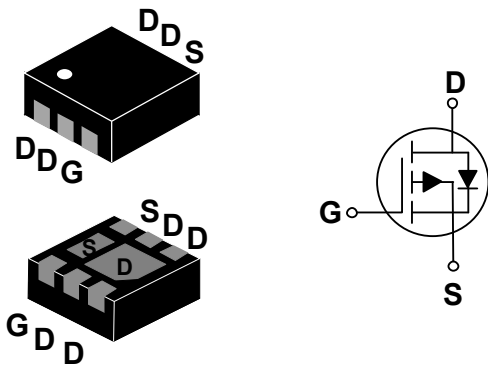
Features

- $R_{DS(ON)} \leq 28m\Omega @ V_{GS} = -4.5V$
- Fast switching
- Green Device Available
- Suit for -1.8V Gate Drive Applications
- Improved dv/dt capability

Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-Held Instruments

DFN2x2-6L Pin Configuration



Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|--------------|--|------------|---------------------|
| V_{DS} | Drain-Source Voltage | -20 | V |
| V_{GS} | Gate-Source Voltage | ± 10 | V |
| I_D | Drain Current - Continuous ($T_c=25^\circ\text{C}$) | -8.5 | A |
| | Drain Current - Continuous ($T_c=100^\circ\text{C}$) | -5.4 | A |
| I_{DM} | Drain Current - Pulsed (NOTE 1) | -34 | A |
| P_D | Power Dissipation ($T_c=25^\circ\text{C}$) | 3.3 | W |
| | Power Dissipation - Derate above 25°C | 0.026 | W/ $^\circ\text{C}$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ\text{C}$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ\text{C}$ |
| Marking Code | | s | |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|---------------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to Ambient | --- | 62 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JC}$ | Thermal Resistance Junction to Case | --- | 38 | $^\circ\text{C}/\text{W}$ |

**Electrical Characteristics (T_J=25°C, unless otherwise noted)****Off Characteristics**

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------|--------------------------------|---|------|------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} = 0V , I _D = -250uA | -20 | --- | --- | V |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} = -20V , V _{GS} = 0V , T _J =25°C | --- | --- | -1 | uA |
| | | V _{DS} = -16V , V _{GS} = 0V , T _J =125°C | --- | --- | -10 | uA |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} = ±10V , V _{DS} = 0V | --- | --- | ±100 | nA |

On Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---------------------|-----------------------------------|--|------|------|------|------|
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} = -4.5V , I _D = -4A | --- | 22 | 28 | mΩ |
| | | V _{GS} = -2.5V , I _D = -3A | --- | 27 | 37 | |
| | | V _{GS} = -1.8V , I _D = -2A | --- | 33 | 45 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D = -250uA | -0.3 | -0.6 | -1 | V |
| g _{fs} | Forward Transconductance | V _{DS} = -10V , I _S = -3A | --- | 8.4 | --- | S |

Dynamic and switching Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---------------------|------------------------------|--|------|------|------|------|
| Q _g | Total Gate Charge | V _{DS} = -10V , V _{GS} = -4.5V , I _D = -4A (NOTE 2、3) | --- | 16.1 | 25 | nC |
| Q _{gs} | Gate-Source Charge | | --- | 1.8 | 3 | |
| Q _{gd} | Gate-Drain Charge | | --- | 3.8 | 7 | |
| T _{d(on)} | Turn-On Delay Time | V _{DD} = -10V , V _{GS} = -4.5V , R _G = 25Ω , I _D = -1A (NOTE 2、3) | --- | 8.2 | 16 | nS |
| T _r | Rise Time | | --- | 30 | 57 | |
| T _{d(off)} | Turn-Off Delay Time | | --- | 71.1 | 135 | |
| T _f | Fall Time | | --- | 19.8 | 38 | |
| C _{ISS} | Input Capacitance | V _{DS} = -15V , V _{GS} = 0V , F= 1MHz | --- | 1440 | 2100 | pF |
| C _{OSS} | Output Capacitance | | --- | 155 | 230 | |
| C _{ISS} | Reverse Transfer Capacitance | | --- | 115 | 170 | |

Drain-Source Diode Characteristics and Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|---------------------------|---|------|------|------|------|
| I _S | Continuous Source Current | V _G = V _D = 0V , Force Current | --- | --- | -8.5 | A |
| I _{SM} | Pulsed Source Current | | --- | --- | -17 | A |
| V _{SD} | Diode Forward Voltage | V _{GS} = 0V , I _S = -1A , T _J = 25°C | --- | --- | -1 | V |

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



Characteristics Curves

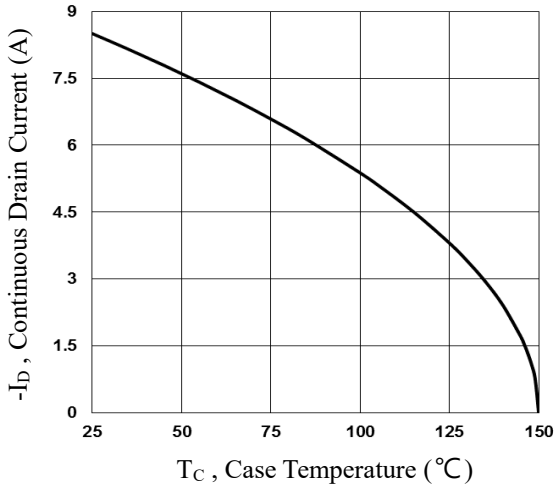


Fig.1 Continuous Drain Current vs. T_c

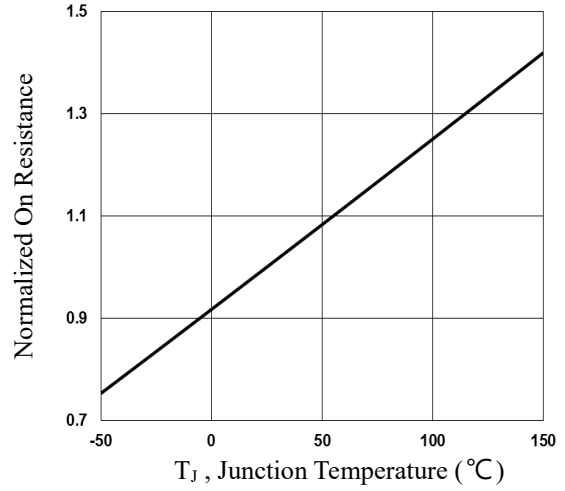


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

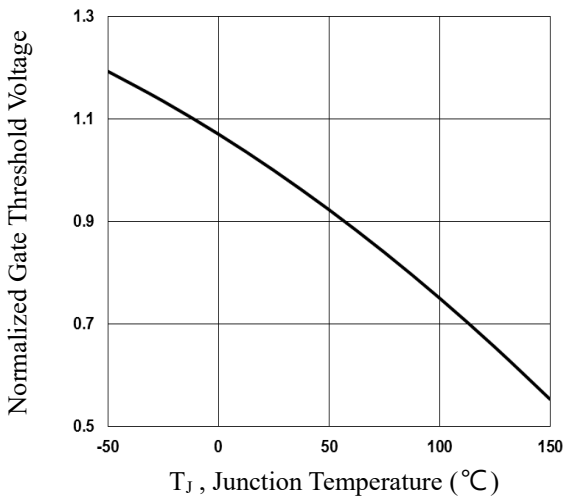


Fig.3 Normalized V_{th} vs. T_j

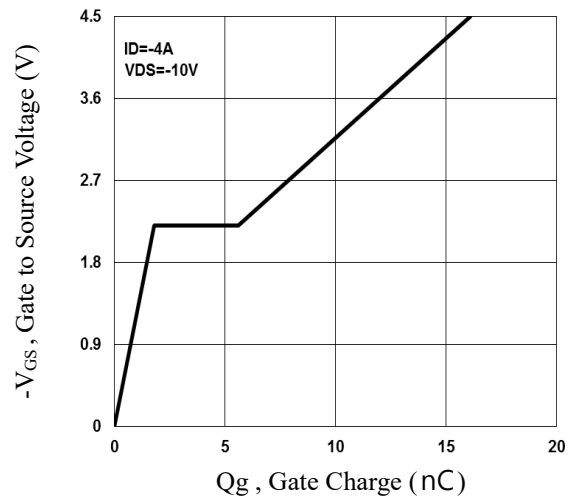


Fig.4 Gate Charge Waveform

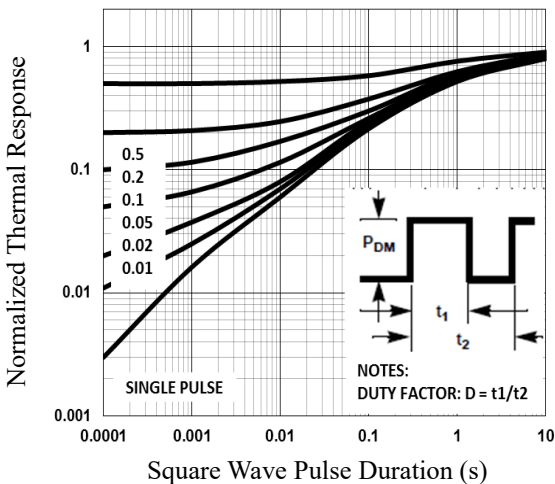


Fig.5 Normalized Transient Impedance

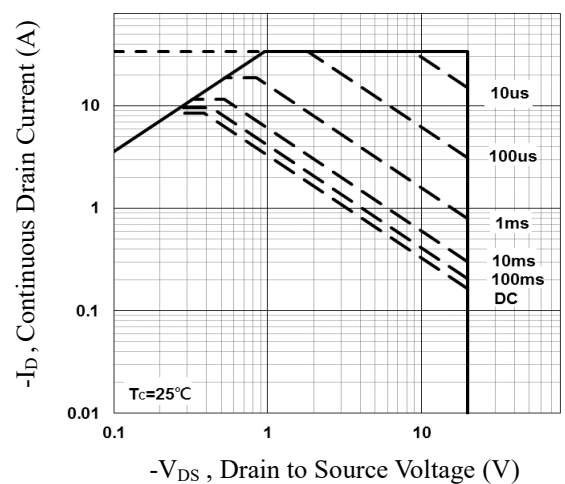


Fig.6 Maximum Safe Operation Area



Characteristics Curves

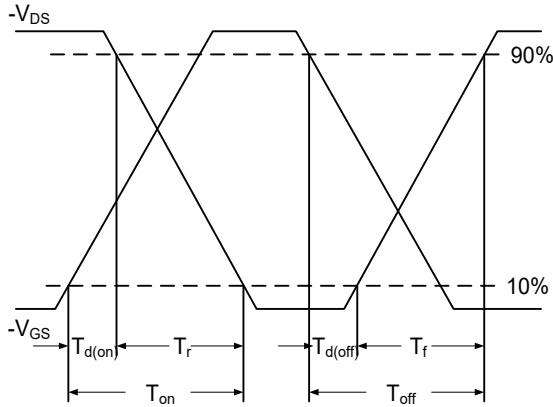


Fig.7 Switching Time Waveform

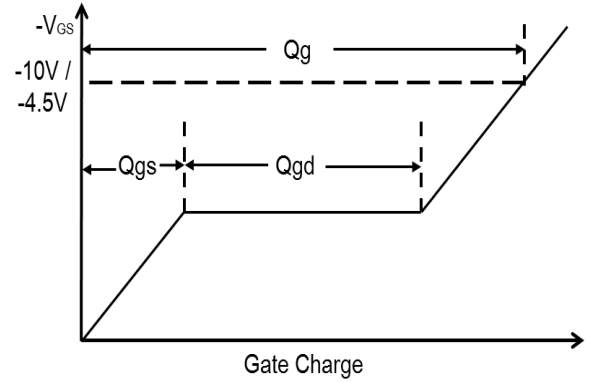
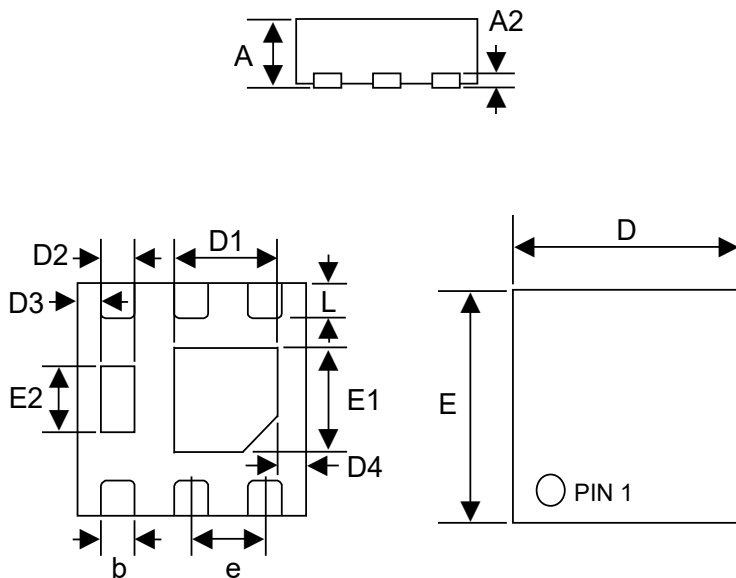


Fig.8 Gate Charge Waveform

Package Outline Dimensions



| Symbol | Dimensions in mm | | Dimensions in inches | |
|--------|------------------|------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 0.50 | 0.80 | 0.019 | 0.032 |
| A2 | 0.152 REF | | 0.006 REF | |
| b | 0.25 | 0.35 | 0.009 | 0.014 |
| D | 1.90 | 2.10 | 0.074 | 0.083 |
| D1 | 0.80 | 1.00 | 0.031 | 0.040 |
| D2 | 0.25 | 0.35 | 0.009 | 0.014 |
| D3 | 0.20 BSC | | 0.008 BSC | |
| D4 | 0.25 BSC | | 0.010 BSC | |
| E | 1.90 | 2.10 | 0.074 | 0.083 |
| E1 | 0.80 | 1.10 | 0.031 | 0.044 |
| E2 | 0.46 | 0.66 | 0.018 | 0.260 |
| e | 0.65 BSC | | 0.026 BSC | |
| L | 0.25 | 0.35 | 0.009 | 0.014 |

DFN2x2-6L



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